

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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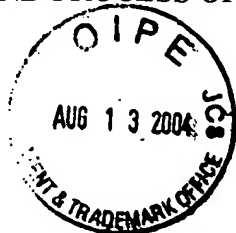
Applicant: Damion T. Searls et al.

Title: A SURFACE MOUNT SOLDER METHOD AND APPARATUS FOR DECOUPLING CAPACITANCE AND PROCESS OF MAKING

Docket No.: 884.766US2

Filed: February 9, 2004

Examiner: Unknown



Serial No.: 10/774955

Due Date: August 10, 2004

Group Art Unit: 2826

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

☒ A return postcard.

☒ A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 1 cited document. US Patent/Publication references NOT enclosed; application filed after June 30, 2003.

☒ Copy of International Search Report in PCT/US03/15972, mailed May 10, 2004 (6 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

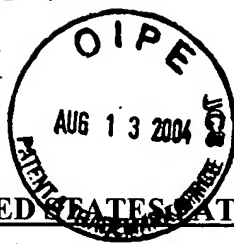
By: Ann M. McCrackin
Atty: Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 10 day of August, 2004.

KACIA LEE
Name

Kacia Lee
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)



S/N 10/774955

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Damion T. Searls et al.	Examiner:	Unknown
Serial No.:	10/774955	Group Art Unit:	2826
Filed:	February 09, 2004	Docket:	884.766US2
Title:	A SURFACE MOUNT SOLDER METHOD AND APPARATUS FOR DECOUPLING CAPACITANCE AND PROCESS OF MAKING		
Assignee:	Intel Corporation	Customer No:	21186

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(1) and 37 C.F.R. §1.97(e)(1), Applicants state that each item of information contained in the Supplemental Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Supplemental Information Disclosure Statement. A copy of the relevant International Search Report in PCT/US03/15972, mailed May 10, 2004, is also enclosed.

It is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if a final action under §1.113, a notice of allowance under §1.311, or an action that otherwise closes prosecution in the application has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No : 10/774955

Filing Date: February 09, 2004

Title: A SURFACE MOUNT SOLDER METHOD AND APPARATUS FOR DECOUPLING CAPACITANCE AND PROCESS OF MAKING

Assignee: Intel Corporation

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Dkt: 884.766US2 (INTEL)

The present application is either a U.S. national patent application filed after June 30, 2003 or an international application that entered the national stage under 35 U.S.C. § 371 after June 30, 2003. Thus, Applicant believes that the U.S. Patent & Trademark Office has waived the requirement under 37 C.F.R. 1.98 (a)(2)(i) for submitting a copy of each cited U.S. patent and each U.S. patent application publication. The waiver is provided in a pre-OG notice from the U.S. Patent & Trademark Office entitled "Information Disclosure Statements May Be Filed Without Copies of U.S. Patents and Published Applications in Patent Applications filed after June 30, 2003" and dated July 11, 2003. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

DAMION T. SEARLS ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Minneapolis, Minnesota 55402
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Date Aug. 9, 2004

By Ann M. McCrackin
Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 10 day of August, 2004.

KACIA LEE
Name

Kacia Lee
Signature

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known	
	Application Number	10/774955
	Filing Date	February 9, 2004
	First Named Inventor	Searls, Damion
	Group Art Unit	2826
	Examiner Name	Unknown
Sheet 1 of 1	Attorney Docket No: 884.766US2	



US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-2002/0017700-A1	02/14/2002	Mori, T. , et al.	257	532	07/05/2001
	US-4,754,366	06/28/1988	Hernandez, J. M.	361	306.2	03/19/1987

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
	WO-0004595A2	01/27/2000	Burton, E. A.	H01L	23/00	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-Issue number(s), publisher, city and/or country where published.	T ²

EXAMINER

DATE CONSIDERED